Product Change Notification

105488 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**105488 - 00**
Change Title:	**32Mb Intel StrataFlash® Memory (J3), PCN 105488-00, FFF, 180nm Lithography conversion**
Date of Publication:	**September 21, 2005**

Type of Change Notification:

FFF - (Form-Fit-Function)

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date of Samples Availability:	Nov 04, 2005
Date of Qualification Data Availability:	Dec 05, 2005
Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 03, 2006
Date of First Availability of Post-Conversion Material:	Jan 03, 2006

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Intel is converting the 32Mb Intel StrataFlash® Memory (J3) products on 180 nm process lithography to 130nm process lithography. The product name on the 130 nm lithography will be 32Mb Intel® Embedded Flash Memory (J3 v. D).

For TSOP packages, the marking will change from an Ink Mark to a Laser Mark. This is consistent with the marking methodology for all other package types. easyBGA packages were previously laser marked and will continue to be laser marked.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to customer applications. The 32Mb Intel® Embedded Flash Memory (J3 v. D) on 130 nm process lithography will meet Intel's quality and reliability standards and is backward compatible with the 32 Mb Intel StrataFlash® Memory (J3) products on 180 nm process lithography. There will be no change to silicon functionality, package ballout, pitch, size or package dimensions.

Intel will be introducing new part numbers and ordering codes for the 130nm lithography product so customers can differentiate the 180nm from the 130nm lithography products. The table below reflects the current (180nm) and equivalent new (130nm) part numbers and ordering codes. In order to aid visual identification of the 130nm lithography product, the portion of the package mark previously denoted as '28F320J3C' will change to '28F320J3D'.

Note:

> *All customers should expect to receive post-conversion material on date of first availability of post-conversion material. Pre-conversion material inventory is expected to be depleted by the date of first availability of post-conversion material.*

Recommended action: It is recommended that the customer order samples now and conduct a validation test.

For further detail, please go to www.intel.com/design/flash and click on "Documentation" from the left navigation for the most current version of the documents listed below:

- o Intel® Embedded Flash Memory (J3 v. D) Datasheet
  URL: http://www.intel.com/design/flcomp/datashts/308551.htm
- o AP-835, Intel StrataFlash® Memory (J3) to Intel® Embedded Flash Memory (J3 v. D) Conversion Guide
  URL: http://www.intel.com/design/flcomp/applnots/308555.htm

Products Affected / Intel Ordering Codes:

TSOP

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#	Post-Conversion Product Code	Post-Conversion Spec/ROM	Post-Conversion MM#
TE28F320J3C110 856508		856508	TE28F320J3D75 872335		872335
TE28F320J3C110 S B48	S B48	855194	TE28F320J3D75 S B48	S B48	872334
TE28F320J3C110 S L7GW	S L7GW	860765	TE28F320J3D75 872335		872335
TE28F320J3C110 S L7GX	S L7GX	860767	TE28F320J3D75 S B48	S B48	872334
TE28F320J3C110 S L7H8	S L7H8	860792	TE28F320J3D75 S B93	S B93	872331

TSOP Lead Free

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#	Post-Conversion Product Code	Post-Conversion Spec/ROM	Post-Conversion MM#
JS28F320J3C110 866096		866096	JS28F320J3D75 872337		872337
JS28F320J3C110 S B48	S B48	866434	JS28F320J3D75 S B48	S B48	872339
JS28F320J3C110 S B93	S B93	866098	JS28F320J3D75 S B93	S B93	872341

easyBGA

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#	Post-Conversion Product Code	Post-Conversion Spec/ROM	Post-Conversion MM#
RC28F320J3C110 856506		856506	RC28F320J3D75 876045		876045
RC28F320J3C110 S B48	S B48	855200	RC28F320J3D75 S B48	S B48	876044
RC28F320J3C110 S L7H2	S L7H2	860769	RC28F320J3D75 876045		876045
RC28F320J3C110 S L7H7	S L7H7	860791	RC28F320J3D75 S B93	S B93	876023

easyBGA Lead Free

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#	Post-Conversion Product Code	Post-Conversion Spec/ROM	Post-Conversion MM#
PC28F320J3C110 862214		862214	PC28F320J3D75 876051		876051
PC28F320J3C110 S B48	S B48	863024	PC28F320J3D75 S B48	S B48	876043
PC28F320J3C110 S B93	S B93	862215	PC28F320J3D75 S B93	S B93	872343

Samples

Sample Product Code	Sample Spec/ROM	Sample MM#	Description
JS28F320J3D75 Q DM0	Q DM0	876055	TSOP LF 96pc tray
JS28F320J3D75 Q DM1	Q DM1	876056	TSOP LF 2pc tube
JS28F320J3D75 Q DM2	Q DM2	876057	TSOP LF 100pc reel
PC28F320J3D75 Q DM6	Q DM6	876052	easyBGA LF 144pc tray
PC28F320J3D75 Q DM7	Q DM7	876053	easyBGA LF 2pc tube
PC28F320J3D75 Q DM8	Q DM8	876054	easyBGA LF 100pc reel
RC28F320J3D75 Q DM3	Q DM3	876047	easyBGA 144pc tray
RC28F320J3D75 Q DM4	Q DM4	876049	easyBGA 2pc tube
RC28F320J3D75 Q DM5	Q DM5	876050	easyBGA 100pc reel
TE28F320J3D75 Q DL7	Q DL7	876022	TSOP 96pc tray
TE28F320J3D75 Q DL8	Q DL8	876020	TSOP 2pc tube
TE28F320J3D75 Q DL9	Q DL9	876021	TSOP 100pc reel

Reference Documents / Attachments:

Document:	**Location #:**

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
September 19, 2005	00	Originally Published PCN